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TITLE: MANUFACTURE OF MULTILAYERED FLEXIBLE
CIRCUIT BOARD

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INVENTOR-INFORMATION:

NAME

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COUNTRY

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N/A

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ABSTRACT:

PURPOSE: To lessen manufacturing processes in number so as to decrease a multilayered flexible circuit board in manufacturing cost by a method wherein insulating films and circuit patterns are alternately printed in lamination on a dissolvable base, and the dissolvable base is dissolved after printing is finished.

CONSTITUTION: A dissolvable base 1 is formed of dry film or the like which can be dissolved in a solvent or an acid.alkali solution. A first conductor

coat 4 which forms a circuit pattern is formed on a the dissolvable base 1 and a first insulting film 2 by printing. The first conductor coat 4 contains connectors 4a which extend from the first insulating film 2 to the dissolvable base 1. In succession, a second insulating film 5 is formed on the first insulating film 2 by printing excluding an opening 6 which is used for electrically connecting an upper circuit pattern and a lower circuit pattern together. A second conductor coat 7 forming a circuit pattern is formed on the second insulating film 5 by printing. A process follows, where a connector 7a of the second conductor coat 7 and a terminal 7b of the second conductor coat 7 exposed through a surface component mounting section 9 are subjected to a surface treatment, and then the dissolvable base 1 is dissolved in a solvent or an acid.alkali solution to separate.

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